

Technical Data Sheet



THICK FILM MATERIALS

Product Type: End Terminations

Product Name: ET2003



Polymer Silver Plateable End Termination

Description

ET2003 is a dippable polymer based silver end termination with a reduced silver content for cost sensitive applications. It contains a fast curing polymer system.

ET2003 is a Pb and Cd free Ni/Sn plateable polymer end termination designed to be compatible on multilayer ceramic chip capacitors (NPO and X7R bodies).

Key Benefits

- Ni and Sn plateable
- Solvent resistant
- Pb and Cd free

Typical Properties

Metal Type
Silver

Adhesion
Excellent Adhesion

Solvent Resistance
Excellent

Viscosity
20 – 40 Kcps Brookfield HBT
SC4 – 14 spindle, 6R utility cup at 10 rpm, 25 °C

% Solids
55.0 ± 1.0 %

Application
A blotting step can be used to control the amount of paste deposited on the chip body, if needed.

Recommended Processing Guidelines

Mixing
Material should be thoroughly mixed prior to use

Cleaning
Clean uncured resin with Acetone or similar solvent

Drying
120 °C for 20 minutes

Curing
185 °C for 60 minutes

Resistance
< 90 mΩ/□ per mil
200 °C for 30 minutes

Thinner:
V-521

Warranty:
Material guaranteed to meet specifications for 3 months from date of shipment.

Handling and Precautions:
Use in a well-ventilated area
Avoid contact with skin
Wash with soap and water

Storage:
Refrigeration a 5 °C required to maintain shelf life.
Allow paste to come to room temperature prior to opening.
Spatulate well before using, as settling may occur during storage.

3 months shelf life at room temperature
6 months shelf life when stored in refrigeration

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